IPC ASSOCIATION CONNECTELECTRONICS INDUSTRI	Material Comp © Copyright 2005. international and Pa	<b>position De</b> IPC, Bannockl an-American c	<b>claration</b> burn, Illinois. A opyright conver	ll rights reserved u	This doc level par					rithin the manufactur level materials for wh					
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Infor	mation														
Company name* Company u			Company uni	any unique ID U			Unique ID Authority					Response Date*			
nsemi											2025-05-14				
Contact Name Title - Contact				ntact			Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards		Product Envi	ro Compliance	ompliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number Mfr Item		n Number Mfr Item Name			Effec	ctive Date	Version	Ma	Manufacturing Site		Veight*	UOM	Unit Type	
				LOG CMOS ML7 LCX157 device w extended temp rai	with lower VCC and	ng 2025-05-14			PH	PH1		5.4	mg	Each	
<b>Ianufacturin</b>	g Proccess Informa	ation													
Terminal Plating / Grid Array Material Termi			erminal Base Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles						
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С	30 se		seconds 3			
omments										•	•	,			
vel 1 - maximun	n time at peak temperat	ure during so	ldering is 10-3	0 seconds											
	ation regarding materia														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.32			Epoxy resin	proprietary data		0.132	mg
			Supplier	Silver (Ag)	7440-22-4		1.056	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.132	mg
Lead Frame	20.76	mg	Supplier	Iron (Fe)	7439-89-6		0.3944	mg
			Supplier	Copper (Cu)	7440-50-8		20.3656	mg
Mold Compound-Black	19.0			Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenolic Resin	Proprietary Data		0.95	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.38	mg
			Supplier	Carbon Black (C)	1333-86-4		0.095	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.625	mg
Plating	2.12		Supplier	Palladium (Pd)	7440-05-3		0.1611	mg
			В	Nickel (Ni)	7440-02-0		1.9292	mg
			Supplier	Gold (Au)	7440-57-5		0.0297	mg
Wire Bond - Au	0.2	mg	Supplier	Gold (Au)	7440-57-5		0.2	mg